TECHNOARTS

WEICAI LCD/LED Bonding Machine

CR-818SH-19M

Here are the specifications for the CR-818SH-19M COF Bonding Machine in points:

1. **Bonding Type: COF (Chip on Film)**
2. **Application: Designed for LCD, LED, and OLED screen repairs**
3. **Precision: High-precision bonding ensures accurate connections between flexible circuits and display panels**
4. **Automation: Automated alignment for consistent and reliable bonding**
5. **Temperature Control: Advanced temperature settings for precise bonding conditions**
6. **Pressure Control: Adjustable pressure settings to accommodate different screen types**
7. **User Interface: Easy-to-use and intuitive interface for smooth operation**
8. **Efficiency: Fast and efficient bonding process to enhance productivity**
9. **Compatibility: Compatible with various screen sizes and types**
10. **Durability: Built for long-term use in demanding professional repair environments**

Device Name	Hot Press Machine
Device Model	CR-818-SH
Device Description	Screen repair equipment, LCD repair equipment, COF/TAB bonding equipment, etc.
Device Uses	This product is used in a variety of FPC, COF, TAB and LCD Panel and PCB combination bonding, is reflected in a variety of sizes LCD vertical, horizontal, vertical band, horizontal belt, black belt, black, colored thread, ribbon , multi-line, black, black and white, vertical half display,horizontal half breakdown maintenance.
Device Features	Single head ,single pneumatic device, single temperature control.
	Multi-speed pulse source design to meet the power requirements of diversified product pressure.
Applicable LCD Panel Specifications	15"-65"(Platform expandable)
Applicable LCD Panel Thickness	0.3MM-1.1MM[Single glass]
Panel Type	TFT
Bonding IC Number	One/PANEL
Bonding Direction	X or Y Unidirection
Bonding Head Size	Replaceable blade according to IC specifications (The original machine is equipped (50*1.4*10mm).
Equipment Process Time	TFT，3.8S/chip
Production Beat	TAB，100pcs/H
Bonding Accuracy	±1.5μm (support 4K)
Highest Positioning Accuracy Setting	±0.5μm
Equipment Requirement Work Environment	Clean, Dust-Free, Clean Room
Supply Pressure	0.1~0.7Mpa Dry air source
Power Supply	AC 220V±10%，50HZ，3500W
Pneumatic Device	Air TAC Original precision cylinder.
Pressure System	Pressure system parallel bar structure eliminates the weight of the indenter,pressure minimum accuracy can up to 0.1 KG,pressure components are using SMC precision components.
Heating Method	Pulse (rapid heating/cooling and auxiliary cooling).

Temperature Control System	Brand:Omron
	Adjustable temperature rise curve with high precision PID auto-tuning.
	The peak temperature : within +/-1degrees Celsius.
	Room temperature time to 180 degrees the response time within 2-3 seconds
Hot Pressing Head	Material: Titanium alloy
	Metal Properties:SUS440C
	Origin: United States
	Plane Precision (hot pressing surface) :0.001mm.
	Plane thickness 0.5 (keep 3 times grinding).
Thermocouple Type	K Type Original US OMEGA wire.
Industrial Control Unit	Panasonic PLC FX—C14T

Programme	Panasonic Image Processing System
Touch Unit	Display control Samkoon dual-core touch screen.
Image Unit	COF Counterpoint: Down counterpoint (Optical Path: Lens> Quartz> ITO Electrode> COF
	PCB Alignment: None (optional installation)
	Number of lens: 2
	Microscope: 200-300 continuous zoom
	COF Display Screen: 9 inches HD
	PCB Front Camera: None (optional installation)
	PCB Alignment display: switchable
COF Trimming Unit	Origin: China
	Rail Type: U-rail
	Accuracy:0.01
	Adjustable Direction: X/Y/R
	R Stroke: coarse adjustment 360 degrees, fine adjustment +/- 5 degrees.
COF Fixture	COF Mechanical clamping type ,Z-direction tilt radius micrometer finetuning.
Lens Spinner Unit	Control Mode: X / Y / Z micrometer control
	Focus Adjustment: Manually adjust the focus
Silicone / Teflon	Manual switching position.
LCD Stage (platform)	Manual slide movement.
Bonding Head Alignment	The cylinder can be set to stop in any position in the upper and lower directions.

Control Method	Touch screen + button operation
Parameter Setting	Can store multiple sets of hot pressing parameters as needed.
Rated Voltage	AC 180-220V
Peak Power	400-1100W (can support 68X1.4X10 wide bonding head)
Maximum Power	1100W
Actual Power	580W
Body Size	1800X1260x1450mm(L*W*H) 860*860*1450mm(L*W*H) Without Platform size.

Net Weight of Equipment	250KG
Number of Packages	2
Equipment Packaging	Wooden Boxes, non-logs (material is glued board, no fumigation is required for export).
Package Size and Gross Weight	1000X900X700mm (L*W*H) 150KG
	1920X240X960mm (L*W*H) 110KG